



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-06-25
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giovanni Giacopello	Representative Title	AMS/IPD Materials Declaration Champion)
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	HD6R*0884ABJ	A	BO2A	2013-06-25
Amount	UoM	Unit type	ST ECOPACK Grade	
54.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	5 - 4.4 - 0.9	14	J bend	
Comment				

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-18 June 2012				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HD6R*0884ABJ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.777	mg	supplier	die	Silicon (Si)	7440-21-3		0.741	mg	953668	13232
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	7722	107
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	1287	18
die (s)				supplier	metallization	Tungsten (W)	7440-33-7		0.006	mg	7722	107
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.002	mg	2574	96
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.015	mg	19305	268
die (s)				supplier	passivation	Gamma-butyrolactone	96-48-0		0.004	mg	5148	71
die (s)				supplier	passivation	Polyhydroxyamide	55295-98-2		0.002	mg	2574	96
Leadframe	Copper & its alloys	24.103	mg	supplier	alloy	Copper (Cu)	7440-50-8		24.057	mg	998092	429589
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.011	mg	456	196
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.02	mg	830	957
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.014	mg	581	250
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	41	18
Die attach	Other Organic Materials	0.294	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.223	mg	758503	9982
Die attach				supplier	glue or tape	2,6-Diglycidylphenyl allyl ether	13561-08-5		0.029	mg	98639	518
Die attach				supplier	glue or tape	1,4-bis (2,3-epoxypropoxy) butane	2425-79-8		0.012	mg	40816	214
Die attach				supplier	glue or tape	2,6-Diglycidyl phenyl allyl ether	CE 417-470-1		0.018	mg	61224	921
Die attach				supplier	glue or tape	Polyoxypropylenediamine	9046-10-0		0.012	mg	40816	214
Bonding wire	Precious metals	0.323	mg	supplier	wire	Gold (Au)	7440-57-5		0.323	mg	1000000	5768
encapsulation	Other Organic Materials	28.503	mg	supplier	mold compound	Silica, vitreous	60676-86-0		25.281	mg	886959	451446
encapsulation				supplier	mold compound	epoxy resin	Proprietary		2.281	mg	80027	40732
encapsulation				supplier	mold compound	Phenol resin	Proprietary		0.855	mg	29997	15268
encapsulation				supplier	mold compound	carbon black	1333-86-4		0.086	mg	9017	1536